U.S. DEPARTMENT OF COMMERCE

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SON-1880 Patent and Trademark Office To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 2. Name and address of receiving party(ies) 1. Name of conveying party(ies) 1. Takeshi NOGAMI Name: KABUSHIKI KAISHA KOBE SEIKO SH 2.Naoki KOMAI 3.Koichi IKEDA 4. Takashi KINOSHITA Internal Address: 5.Kohei SUZUKI 6.Nobuyuki KAWAKAMI 7. Yoshito FUKUMOTO Additional name(s) of conveying party(ies) attached No Street Address: 3-18, Wakinohama-cho 1-chome, Chuo-ku. Kobe-3. Nature of conveyance: shi, HYOGO 651-0072 Japan **☒** Assignment □ Merger City: KOBE, JAPAN ☐ Security Agreement ☐ Change of Name Additional name(s) & address(es) attached  $\boxtimes$  Yes  $\square$  No Other Execution Date: (1-3) July 26, 2000 and (4-7) July 6, 2000 09/652362 4. Application number(s) or patent number(s): If the document is being filed together with a new application, the execution date of the application is (1-3) July 26, 2000 and (4-7) July 6. 2000 Additional numbers attached No 5. Name and address of party to whom correspondence concerning 6. Total number of applications and patents involved: ..... 1 document should be mailed: Name: Ronald P. Kananen, Esq. 7. Total fee (37 CFR 3.41).....\$ 40.00 Internal Address: RADER, FISHMAN & GRAUER Enclosed Suite 501 MAuthorized to be charged to Deposit Account 1233 20th Street, NW Street Address: 8. Deposit account umber: 18-0013 City: Washington, D.C. Zip: 20036 (Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE

9. Statement and signature.

FORM PTO-1984

To the best of my knowledge and belief, the foregoing information is the and correct and any attached copy is a true copy of the original document.

Ronald P. Kananen

Name of Person Signing

Total number of pages comprising cover sheet 1

August 30, 2000

Date

2 of 2 Assignees

Signature

**PATENT** 

REEL: 011070 FRAME: 0228

Docket	Number:	

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in METHOD OF FORMING BURIED WIRING, AND APPARATUS FOR PROCESSING SUBSTRATUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION , with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, TOKYO 141-0001 JAPAN and KABUSHIKI KAISHA KOBE SEIKO SHO with offices at 3-18, Wakinohama-cho 1-chome, Chuo-ku, Kobe-shi, HYOGO 651-0072 JAPAN , (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements

PATENT REEL: 011070 FRAME: 0229 in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

		And	I	here	by a	auth	ori	ze	and	requ	uest	my	att	orne	ey(s)	of
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Number	:						, F:	ili	.ng I	Date	:					

This assignment executed on the dates indicated below.

Takeshi NOGAMI	<del>_</del>	26, 2000
Name of first inventor	Execution date of	U.S. Patent Application
Signature of first inventor	July	26, 2000
Signature of Ofirst inventor	Date	of this assignment
Naoki KOMAI	July	26, 2000
Name of second inventor	Execution date of	U.S. Patent Application
Signature of second inventor		26, 2000
Signature of second inventor	Date	of this assignment
Koichi IKEDA	July	26, 2000
Name of third inventor	Execution date of	U.S. Patent Application
Signature of third inventor		26, 2000
Signature of third inventor	Date	of this assignment
Takashi KINOSHITA	July	6, 2000
Name of fourth inventor	Execution date of	U.S. Patent Application
7. Kimskila Signature of fourth inventor	<del>-</del>	6, 2000
Signature of fourth inventor	Date	of this assignment

PATENT REEL: 011070 FRAME: 0230

Kohei SUZUKI	July 6, 2000
Name of fifth inventor	Execution date of U.S. Patent Application
Signature of fifth inventor	July 6, 2000
Signature of fifth Inventor	Date of this assignment
Nobuyuki KAWAKAMI	July 6, 2000
Name of sixth inventor	Execution date of U.S. Patent Application
Signature of sixth inventor	July 6, 2000
Signature of sixth inventor	Date of this assignment
Yoshito FUKUMOTO	July 6, 2000
Name of seventh inventor	Execution date of U.S. Patent Application
Moderato Futuro	July 6, 2000
Signature of seventh invento	Date of this assignment

**RECORDED: 08/30/2000** 

PATENT REEL: 011070 FRAME: 0231